

Filename: PMP8726RevA - BoM.xls

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16..24V --> 14.0V @ 5.0A

Quantity	Designator	Value	Description	Package	Part Number	Manufacturer
4	C1, C2, C3,	4.7uF	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1210	1210	GRM32ER71H475KA88L	MuRata
1	C4	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X7R, 0603	0603	C0603C104K8RACTU	Kemet
1	C5	390pF	CAP, CERM, 390pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H391KA01D	MuRata
1	C8	270pF	CAP, CERM, 270pF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H271KA01D	MuRata
1	C9	1uF	CAP, CERM, 1uF, 50V, +/-10%, X7R, 1206	1206	GRM31MR71H105KA88L	MuRata
1	C12	220uF	CAP, AL, 220uF, 25V, +/-20%, 0.16 ohm, SMD	SMT Radial F	EEE-FK1E221P	Panasonic
1	D1	STPS5L60	Diode, Schottky, 5A, 60V	DO-201AB	STPS5L60	ST
2	J1, J2	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	OST
2	J3, J4		Header, TH, 100mil, 2x1, Gold plated	TSW-102-07-G-S	TSW-102-07-G-S	Samtec, Inc.
1	L1	10uH	Inductor, Powdered Iron, 10uH, 10A, 17mOhm	13.9x7.0x13.5mm	SRP1270-100M	Bourns
1	R1	294k	RES, 294k ohm, 1%, 0.1W, 0603	0603	CRCW0603294KFKEA	Vishay-Dale
1	R2	24.9k	RES, 24.9k ohm, 1%, 0.1W, 0603	0603	CRCW060324K9FKEA	Vishay-Dale
1	R3	243k	RES, 243k ohm, 1%, 0.1W, 0603	0603	CRCW0603243KFKEA	Vishay-Dale
2	R4, R5	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
1	R6	6.04k	RES, 6.04k ohm, 1%, 0.1W, 0603	0603	CRCW06036K04FKEA	Vishay-Dale
1	R7	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
3	TP1, TP3, TP6	Red	Test Point, TH, Multipurpose, Red	Keystone5010	5010	Keystone
3	TP2, TP4, TP8	Black	Test Point, TH, Multipurpose, Black	Keystone5011	5011	Keystone
1	TP5	Yellow	Test Point, TH Multipurpose, Yellow	Keystone5014	5014	Keystone
1	TP7	Orange	Test Point, TH, Multipurpose, Orange	Keystone5013	5013	Keystone
1	U1	TPS54540DD	IC, 42V, 5A, Current Mode, Non-Sync Buck	SON	TPS54540DDA	Texas Instruments

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